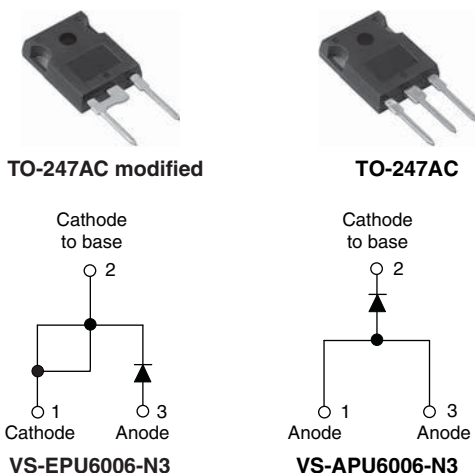


Ultrafast Soft Recovery Diode, 60 A FRED Pt®



FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

DESCRIPTION / APPLICATIONS

VS-EPU60/VS-APU60... series are the state of the art ultrafast recovery rectifiers designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, welding, UPS, DC/DC converters as well as freewheeling diodes in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

PRODUCT SUMMARY

Package	TO-247AC modified (2 pins), TO-247AC
$I_{F(AV)}$	60 A
V_R	600 V
V_F at I_F	1.05 V
t_{rr} typ.	32 ns
T_J max.	175 °C
Diode variation	Single die

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Repetitive peak reverse voltage	V_{RRM}		600	V
Average rectified forward current in DC	$I_{F(AV)}$	$T_C = 116\text{ °C}$	60	A
Single pulse forward current	I_{FSM}	$T_C = 25\text{ °C}$	600	
Operating junction and storage temperatures	T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	V_{BR}, V_R	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage	V_F	$I_F = 60\text{ A}$	-	1.2	1.5	
		$I_F = 60\text{ A}, T_J = 125\text{ °C}$	-	1.1	1.3	
		$I_F = 60\text{ A}, T_J = 175\text{ °C}$	-	1.05	1.2	
Reverse leakage current	I_R	$V_R = V_R$ rated	-	-	30	μA
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	200	
Junction capacitance	C_T	$V_R = 600\text{ V}$	-	38	-	pF



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t _{rr}	I _F = 1 A, dI _F /dt = 200 A/μs, V _R = 30 V		-	32	43	ns
		T _J = 25 °C	I _F = 60 A dI _F /dt = 200 A/μs V _R = 200 V	-	110	-	
		T _J = 125 °C		-	200	-	
Peak recovery current	I _{RRM}	T _J = 25 °C		-	10	-	A
		T _J = 125 °C		-	19	-	
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	530	-	nC
		T _J = 125 °C		-	1900	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	T_J , T_{Stg}		-65	-	175	$^{\circ}\text{C}$
Thermal resistance, junction to case	R_{thJC}		-	-	0.65	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-	
Weight			-	6	-	g
			-	0.21	-	oz.
Mounting torque			6 (5)	-	1.2 (10)	kgf. cm (lbf · in)
Marking device		Case style TO-247AC modified	EPU6006			
		Case style TO-247AC	APU6006			

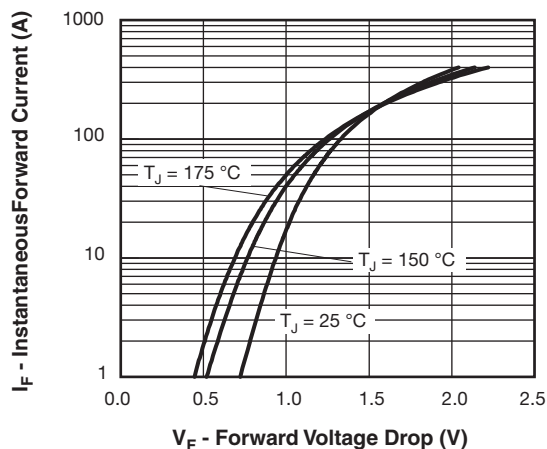


Fig. 1 - Typical Forward Voltage Drop Characteristics

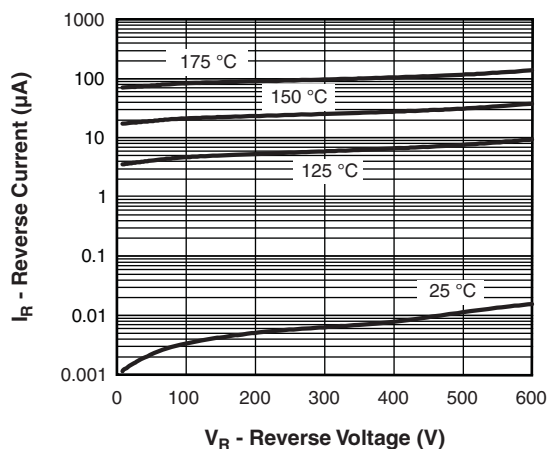


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

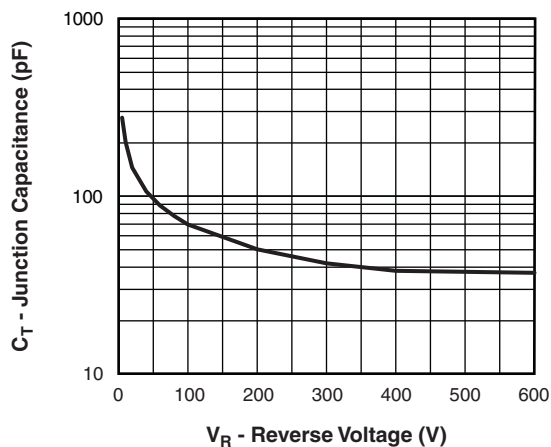
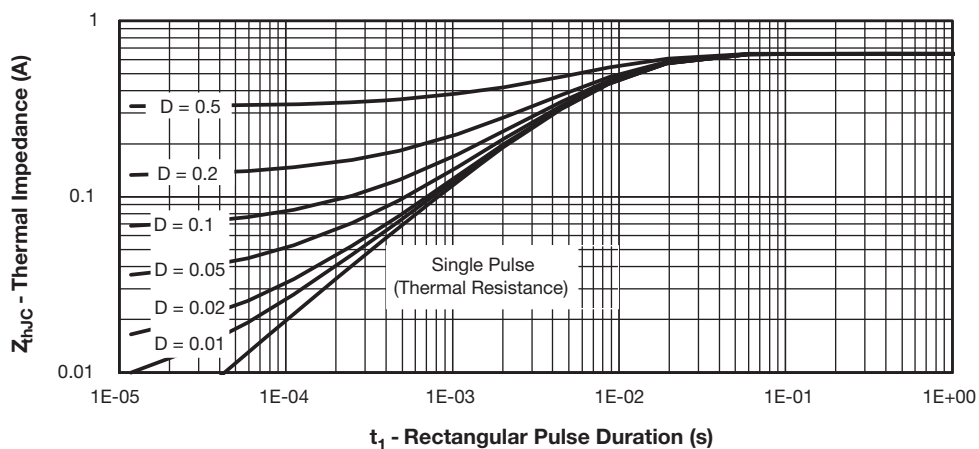


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

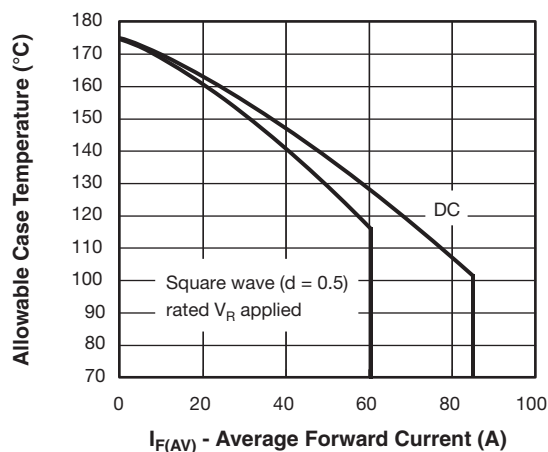


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

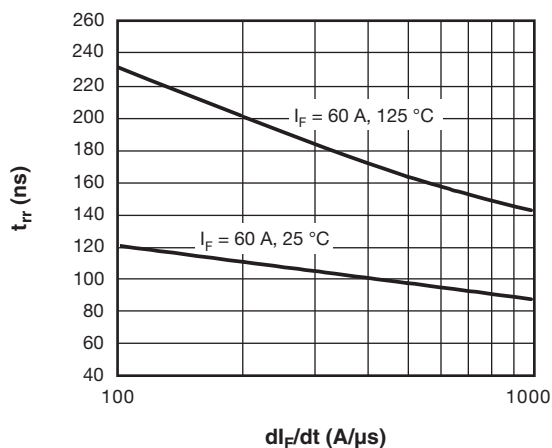


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

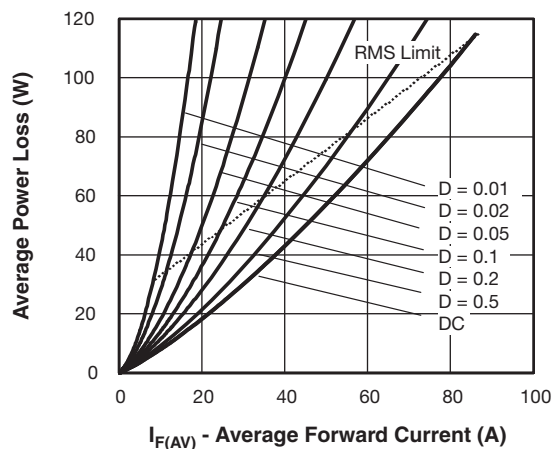


Fig. 6 - Forward Power Loss Characteristics

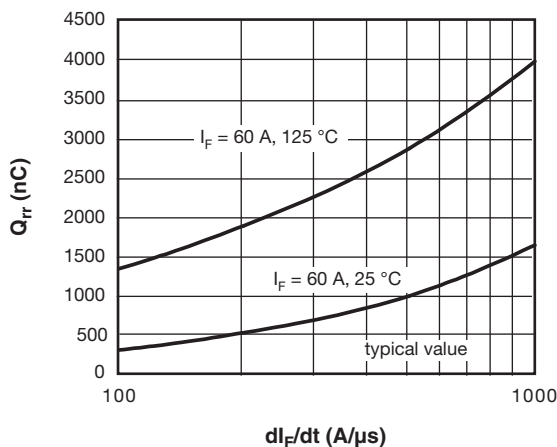


Fig. 8 - Typical Stored Charge vs. dI_F/dt

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 P_{dREV} = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R

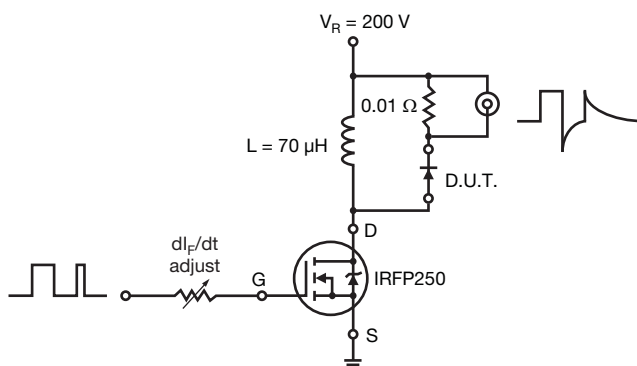


Fig. 9 - Reverse Recovery Parameter Test Circuit

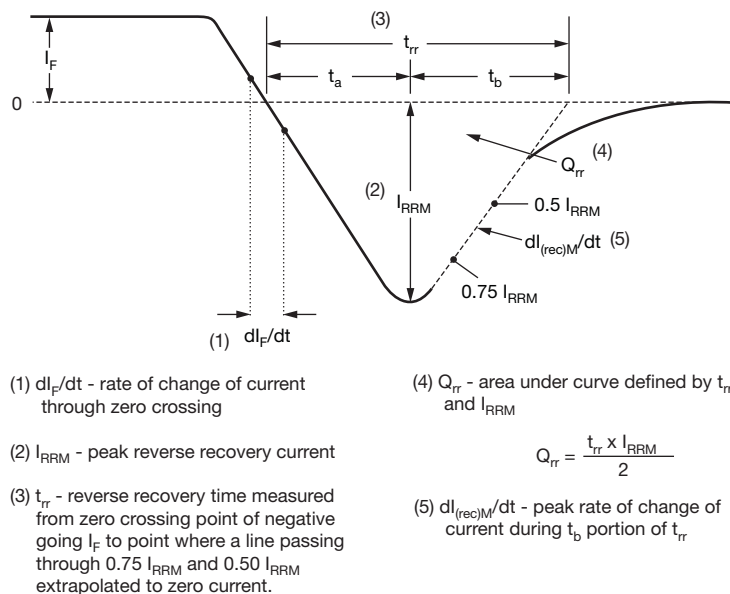


Fig. 10 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	VS-	E	P	U	60	06	-N3
	1	2	3	4	5	6	7
1	- Vishay Semiconductors product						
2	- Circuit configuration: A = single diode E = single diode (modified)						
3	- P = TO-247AC						
4	- U = ultrafast recovery time						
5	- Current code (60 = 60 A)						
6	- Voltage code (06 = 600 V)						
7	- Environmental digit: -N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free						

ORDERING INFORMATION (Example)

PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-EPU6006-N3	25	500	Antistatic plastic tube
VS-APU6006-N3	25	500	Antistatic plastic tube

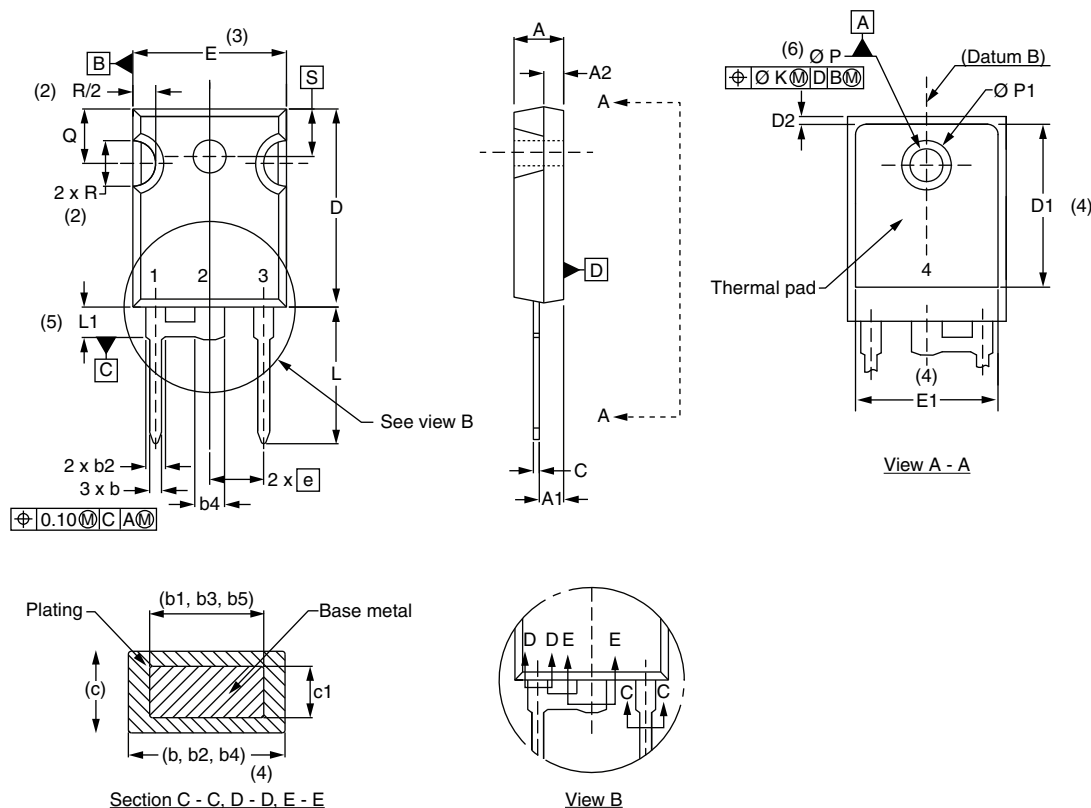
LINKS TO RELATED DOCUMENTS

Dimensions	TO-247AC modified	www.vishay.com/doc?95541
	TO-247AC	www.vishay.com/doc?95542
Part marking information	TO-247AC modified	www.vishay.com/doc?95442
	TO-247AC	www.vishay.com/doc?95007



TO-247AC modified - 50 mils L/F

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.17	1.37	0.046	0.054	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
c	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D2	0.51	1.35	0.020	0.053	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
e	5.46 BSC		0.215 BSC		
Ø K	0.254		0.010		
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
Ø P	3.56	3.66	0.14	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		

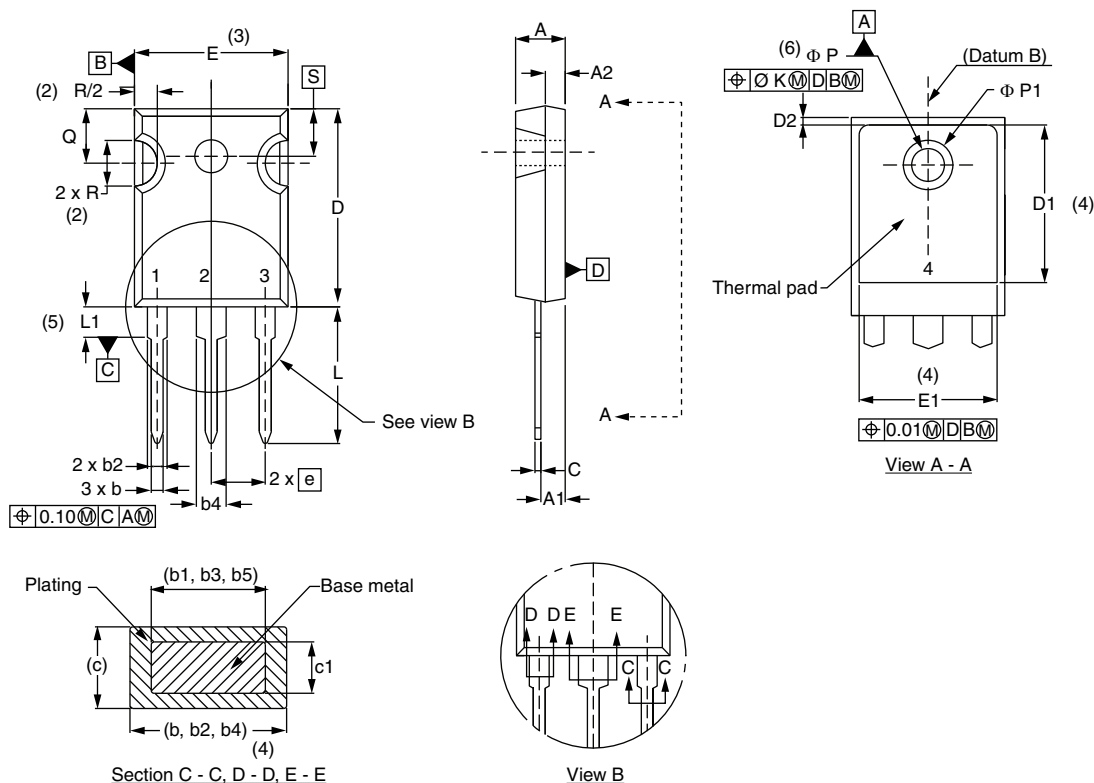
Notes

- Dimensioning and tolerance per ASME Y14.5M-1994
- Contour of slot optional
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- Thermal pad contour optional with dimensions D1 and E1
- Lead finish uncontrolled in L1
- Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q



TO-247AC - 50 mils L/F

DIMENSIONS in millimeters and inches



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